XN06116 (XN6116)

Silicon PNP epitaxial planer transistor

For switching/digital circuits

Features

- Two elements incorporated into one package. (Transistors with built-in resistor)
- Reduction of the mounting area and assembly cost by one half.

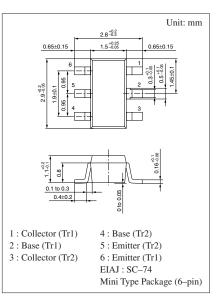
Basic Part Number of Element

• UNR1116(UN1116) \times 2 elements

| Parameter | | Symbol | Ratings | Unit |
|-------------------------|------------------------------|------------------|-------------|------|
| Rating of element | Collector to base voltage | V _{CBO} | -50 | V |
| | Collector to emitter voltage | V _{CEO} | -50 | V |
| | Collector current | I _C | -100 | mA |
| Overall | Total power dissipation | P _T | 300 | mW |
| | Junction temperature | Tj | 150 | °C |
| | Storage temperature | T _{stg} | -55 to +150 | °C |
| | | | | |

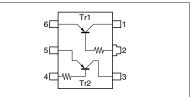
Absolute Maximum Ratings (Ta=25°C)

Electrical Characteristics (Ta=25°C)



Marking Symbol: 6Y

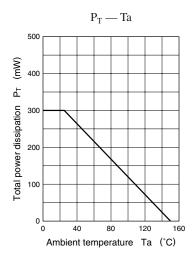
Internal Connection

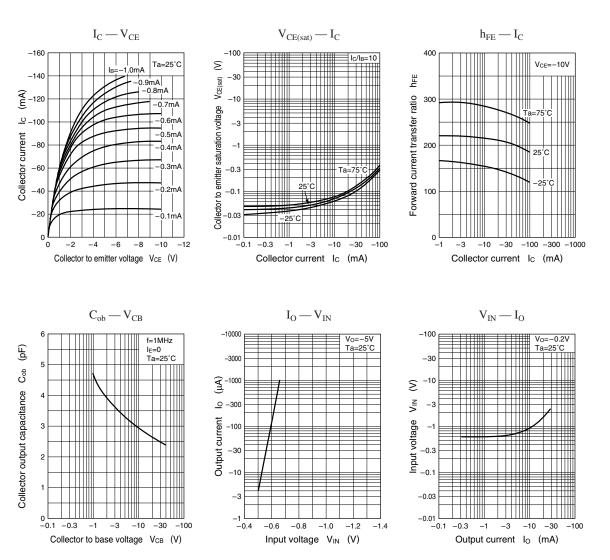


Conditions Parameter Symbol min max Unit typ $I_{\rm C} = -10\mu A, I_{\rm E} = 0$ V Collector to base voltage V_{CBO} -50V Collector to emitter voltage V_{CEO} $I_{C} = -2mA, I_{B} = 0$ -50 $V_{CB} = -50V, I_E = 0$ -0.1μΑ I_{CBO} Collector cutoff current $V_{CE} = -50V, I_B = 0$ -0.5μΑ ICEO $V_{EB} = -6V, I_C = 0$ Emitter cutoff current I_{EBO} -0.01mA $V_{CE} = -10V, I_C = -5mA$ Forward current transfer ratio 160 460 h_{FE} hFE (small/large)*1 $V_{CE} = -10V, I_C = -5mA$ 0.5 0.99 Forward current transfer h_{FE} ratio Collector to emitter saturation voltage V_{CE(sat)} $I_{C} = -10mA$, $I_{B} = -0.3mA$ -0.25V $V_{CC} = -5V, V_B = -0.5V, R_L = 1k\Omega$ V Output voltage high level VOH -4.9 $V_{CC} = -5V, V_B = -2.5V, R_L = 1k\Omega$ V Output voltage low level VOL -0.2 $V_{CB} = -10V, I_E = 1mA, f = 200MHz$ MHz Transition frequency $f_{T} \\$ 80 Input resistance -30% 4.7 R_1 +30% kΩ

*1 Ratio between 2 elements

Note.) The Part number in the Parenthesis shows conventional part number.





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